

**Final Product Change Notification**

202103010F01

**Issue Date:** 28-May-2021

**Effective Date:** 26-Aug-2021

Here's your personalized quality information concerning products Premier Farnell PLC purchased from Nexperia.

For More details Please Contact your respective Nexperia CSR/AM.



**Management Summary**

Introduction of Cu wire and supply extension by release of 200mm wafer diameter to ESD protection devices in SOT23.

Some products receive new die design and change of wafer backside metallization.

**Change Category**

<input checked="" type="checkbox"/> Wafer Fab Process	<input checked="" type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Test Location	<input checked="" type="checkbox"/> Design
<input checked="" type="checkbox"/> Wafer Fab Materials	<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Process	<input type="checkbox"/> Errata
<input type="checkbox"/> Wafer Fab Location	<input type="checkbox"/> Assembly Location	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Equipment	<input type="checkbox"/> Electrical spec./Test coverage

Transfer of ESD protection devices in SOT23 to Cu-wire

**Details of this Change**

Scheduled changes affect ESD protection devices in SOT23. These include:

- bond wire material will be changed from gold (Au) to copper (Cu). Gold wire remains qualified for supply security reason
- for some products, 200mm wafers will be introduced in additional to currently released 150mm wafers
- for some products, new die design and back side metallization will be implemented

Qualifications were made according to:

- AEC-Q101, rev. D
- AEC-Q006, rev. A

Please use the below link(s) to access related documentation to this change notification:

[https://qcm.nexperia.com/change-notification-epcn/PCN\\_SQR\\_202103010F01\\_final\\_20210525.pdf](https://qcm.nexperia.com/change-notification-epcn/PCN_SQR_202103010F01_final_20210525.pdf)

### **Why do we Implement this Change**

Nexperia continues to introduce copper bonding wire for plastic SMD packages to enhance mechanical properties and maintain latest wire bonding technology.

Release of 200mm wafer diameter material will help to safeguard supply chain.

### **Identification of Affected Products**

Changed products can be identified by datecode after implementation

## **Product Availability**

### **Sample Information**

Samples are available upon request

### **Production**

Planned first shipment 26-Aug-2021

## **Impact**

no impact to the product's functionality anticipated.

### **Disposition of Old Products**

Existing inventory will be shipped until depleted

## **Additional information**

### **Timing and Logistics**

Your acknowledgement of this change, conform JEDEC J-STD-046, is expected till 27-Jun-2021. Lack of acknowledgement of the PCN constitutes acceptance of the change.

## **Contact and Support**

For all Quality Notification content inquiries, please contact your local Nexperia Sales Support team.

In case of distribution, please contact your distribution partner.

At Nexperia B.V. we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

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